

Solutions for printed circuit boards

Innovative adhesives and sealants for effective production

- Conformal Coating
- SMD adhesives
- Glob-top
- Flip-chip underfill
- Silicones
- UV/UV LED lamps
- Thermally and electrically conductive adhesives
- UV and/or thermally curing adhesives
- Isotropic and anisotropic adhesives
- Leading equipment technology
- Complete solutions from a single source

Conductive adhesives, die bonding, anisotropic bonding

Panacol-Elosol supplies a range of superior electrically and thermally conductive adhesives. Its applications range from die bonding, antenna contacting, flip-chips through anisotropic bonds and bonding of heatsinks to HF shielding and 3D-MID.

Elecolit® 6604
Vitralit® 6138
Elecolit® 3653
Elecolit® 3043
Elecolit® 3063
Elecolit® 3065

Therm. conductive, measuring instrument sensors
 Therm. conductive, die-attach, heatsink bonding
 Electr. conductive, flexible parts bonding
 Electr. conductive, antenna print, ceramic fuses
 Anisotropic, UV-curing, for flexible circuits
 Anisotropic, dual cure, for flexible circuits

SMD adhesives, flip-chip underfill

Panacol SMD adhesives are ideal for attaching both large and small components on printed circuit boards.

Panacol underfillers are the perfect choice for components such as FC CSPs and FC BGAs for ASICs. Advantages: fast flow behaviour; spread readily under large chips; no cracking, even after thermal shock.

Vitralit® 6104VT
Structalit® 5604
Structalit® 5605
Structalit® 8801 UF
Vitralit® 2655
Vitralit® 2665

Mounting large compon. on PCBs, corner bonding
 SMD, fast curing, excellent adhesion
 SMD, fast curing, excellent adhesion
 Underfill for BGAs, flow way customized
 Flip-chip underfill, flexible, ideal for parts subjected to impact testing
 Flip-chip underfill, very low CTE, Nano-Filler

Conformal coating, glob-top, frame & fill

To protect PCBs and chips from environmental factors, Panacol has developed special conformal coatings. These have already been proven in many applications in the automotive, electronics, medical systems and other industries. Our product expertise also covers glob-top sealants and frame & fill.

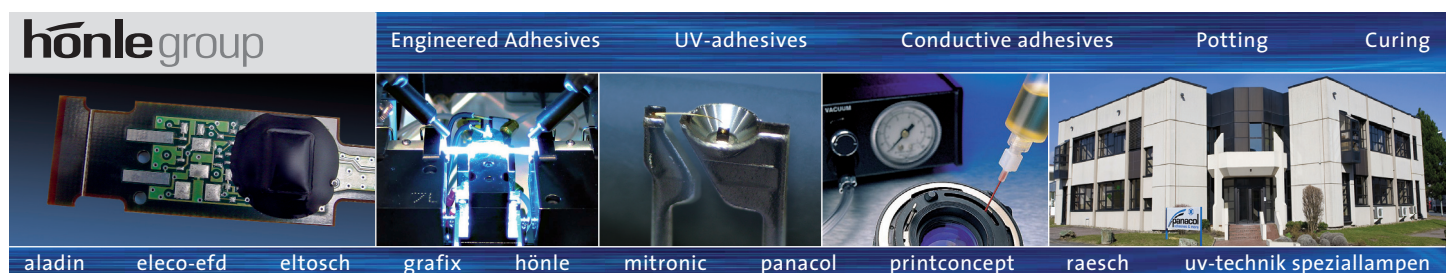
Vitralit® 2009 F
Vitralit® 2004 F
Vitralit® 4451
Vitralit® 1691
Vitralit® 1657
Structalit® 5891
Vitralit® 1671
Vitralit® 1680
Vitralit® 1688

Conf. coating, flexible, UV- and thermally curing
 Liquid, flexible, conf. coating, UV- and therm. curing
 Conf. Coating, foil bonding, low shrinkage
 Glob-top, black, high temperature resistance
 Glob-top, for large/tall parts, thixotropic
 Glob-top, black, excellent adhesion
 Frame mass, stable, can be used wet-in-wet
 Glob-top for smart card chips
 Glob-top for smart card chips

UV/UV LED technology

Hönle UV and UV LED lamps are perfectly matched to Panacol's high tech adhesives to ensure rapid bonding at an optimum quality. They are ideally suited for curing Panacol's adhesives, coatings and sealants.

Hönle system solutions provide excellent technical competence and process reliability. With their new generation of LED arrays and LED flood lamps Hönle offers an innovative technology both for UV and visible light curing without generating heat.



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